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2814

MS NON-FEE AMENDMENT  
PATENT  
8040-1036

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Masamoto TAGO et al.

Serial No. 10/000,020

Filed December 4, 2001

METHOD FOR LAMINATING AND MOUNTING  
SEMICONDUCTOR CHIP

Conf. 7977

Group 2814 ✓

Examiner Dilinh P. Nguyen

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JUL 25 2003  
TECHNOLOGY CENTER 2800

AMENDMENT

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

July 23, 2003

Sir:

Responsive to the Official Action of April 23, 2003,  
please amend the above-identified application as follows:

Make of record the accompanying verified translation of  
our Japanese priority application No. 2000-368539, filed December  
4, 2000.

**Remarks/Arguments** begin on page 2 of this paper.